

# TLC69638-Q1 Automotive, 100mA, 48-Channel LED Driver With Integrated Oscillator and Advance Diagnostics

## 1 Features

- AEC-Q100 qualified for automotive applications
  - Grade 1: –40°C to 125°C ambient operating temperature
  - Device HBM classification level H1C
  - Device CDM classification level C4B
- **Functional Safety-Compliant**
  - Developed for functional safety applications
  - Documentation available to aid ISO 26262 system design up to ASIL B targeted
- 48 integrated current sinks
  - Programmable 16-bit PWM / hybrid dimming
  - Programmable 7-bit analog dot correction (DC)
  - Maximum output current, voltage: 100mA, 16V
- Integrated 33MHz oscillator
  - 16-bit PWM output in 500Hz
  - > 20KHz refresh rate with enhanced spectrum (ES) PWM
- High-speed communication
  - Serial peripheral interface (SPI)
  - Data rates up to 17Mbps
- Power efficiency optimization
  - Adaptive headroom voltage control (AHVC)
  - Device power save mode (PSM)
- EMI mitigation
  - Interface: programmable buffer driving capability
  - Current sinks: phase shifting / spread spectrum
- Protection and diagnostic
  - LED: open / short detection / health check
  - Current sink: adjacent-pin short / health check
  - Interface: CRC / command error / time-out error / communication watchdog
  - Device: under voltage / ISET out of range / thermal shutdown / memory CRC / OTP CRC / OSC watchdog

## 2 Applications

- Automotive central information display
- Automotive cluster display
- Automotive head-up display

## 3 Description

The TLC69638-Q1 is an LED driver with 48 constant current sink channels, which can provide up to 16-bit individual pixel-level LED PWM control. The additional 7-bit dot correction (DC) is also implemented to each channel to control peak current. Each device shares data stream by serial peripheral interface (SPI), which supports up to 511 devices connection. The interface is **software compatible with LED drivers in the same group** which can be applied to different application scenarios based on LED current and total LED number.

To optimize overall systematic power efficiency, the device is equipped with adaptive headroom voltage control (AHVC) scheme to optimize headroom voltage across each channel and device. Only the OUT47 pin from the last device of daisy chain is required to be programmed as FB pin to optimize LED supply voltage from DC/DC.

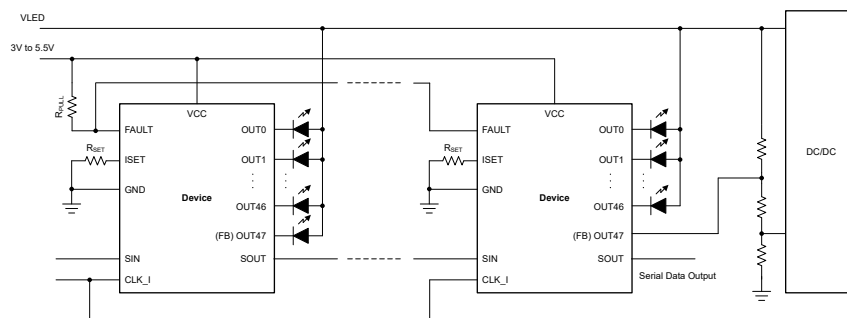
The TLC69638-Q1 is equipped diagnostics for LED, current sink, communication, and device.

### Package Information

| PART NUMBER | PACKAGE <sup>(1)</sup>            | PACKAGE SIZE <sup>(2)</sup> |
|-------------|-----------------------------------|-----------------------------|
| TLC69638-Q1 | RTQ (VQFN, 56)<br>wetttable flank | 8mm × 8mm                   |
|             | DCA (HTSSOP, 56)                  | 14mm × 8.1mm                |
|             | DFD (HTSSOP, 56)                  |                             |

(1) For more information, see [Section 7](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.



**Simplified Schematic**



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## 4 Device Comparison

| PART NUMBER                | CHANNEL NUMBER | MAX. CHANNEL CURRENT | FUNCTIONAL SAFETY CLASSIFICATION | INTERFACE | SOFTWARE COMPATIBLE |
|----------------------------|----------------|----------------------|----------------------------------|-----------|---------------------|
| TLC69621-Q1 <sup>(1)</sup> | 8              | 60mA                 | Functional Safety-Capable        | SPI       | Group 1             |
| TLC69624-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69627-Q1                | 48             |                      |                                  |           |                     |
| TLC69631-Q1 <sup>(1)</sup> | 8              | 100mA                |                                  |           |                     |
| TLC69634-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69637-Q1                | 48             |                      |                                  |           |                     |
| TLC69622-Q1 <sup>(1)</sup> | 8              | 60mA                 | Functional Safety-Compliant      | SPI       | Group 2             |
| TLC69625-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69628-Q1                | 48             |                      |                                  |           |                     |
| TLC69632-Q1 <sup>(1)</sup> | 8              | 100mA                |                                  |           |                     |
| TLC69635-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69638-Q1                | 48             |                      |                                  |           |                     |
| TLC69623-Q1 <sup>(1)</sup> | 8              | 60mA                 | Functional Safety-Compliant      | CSI       | Group 3             |
| TLC69626-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69629-Q1                | 48             |                      |                                  |           |                     |
| TLC69633-Q1 <sup>(1)</sup> | 8              | 100mA                |                                  |           |                     |
| TLC69636-Q1 <sup>(1)</sup> | 24             |                      |                                  |           |                     |
| TLC69639-Q1                | 48             |                      |                                  |           |                     |

(1) Product preview

## 5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 5.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 5.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision * (January 2025) to Revision A (July 2025)           | Page |
|----------------------------------------------------------------------------|------|
| • Changed document status from Advance Information to Production Data..... | 1    |

## 7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable part number           | Status<br>(1) | Material type<br>(2) | Package   Pins    | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|---------------------------------|---------------|----------------------|-------------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">TLC69638QDCARQ1</a> | Active        | Production           | HTSSOP (DCA)   56 | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 125   | TLC69638Q1          |
| TLC69638QDCARQ1.A               | Active        | Production           | HTSSOP (DCA)   56 | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 125   | TLC69638Q1          |
| <a href="#">TLC69638QRTQRQ1</a> | Active        | Production           | QFN (RTQ)   56    | 3500   LARGE T&R      | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 125   | 69638Q1             |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

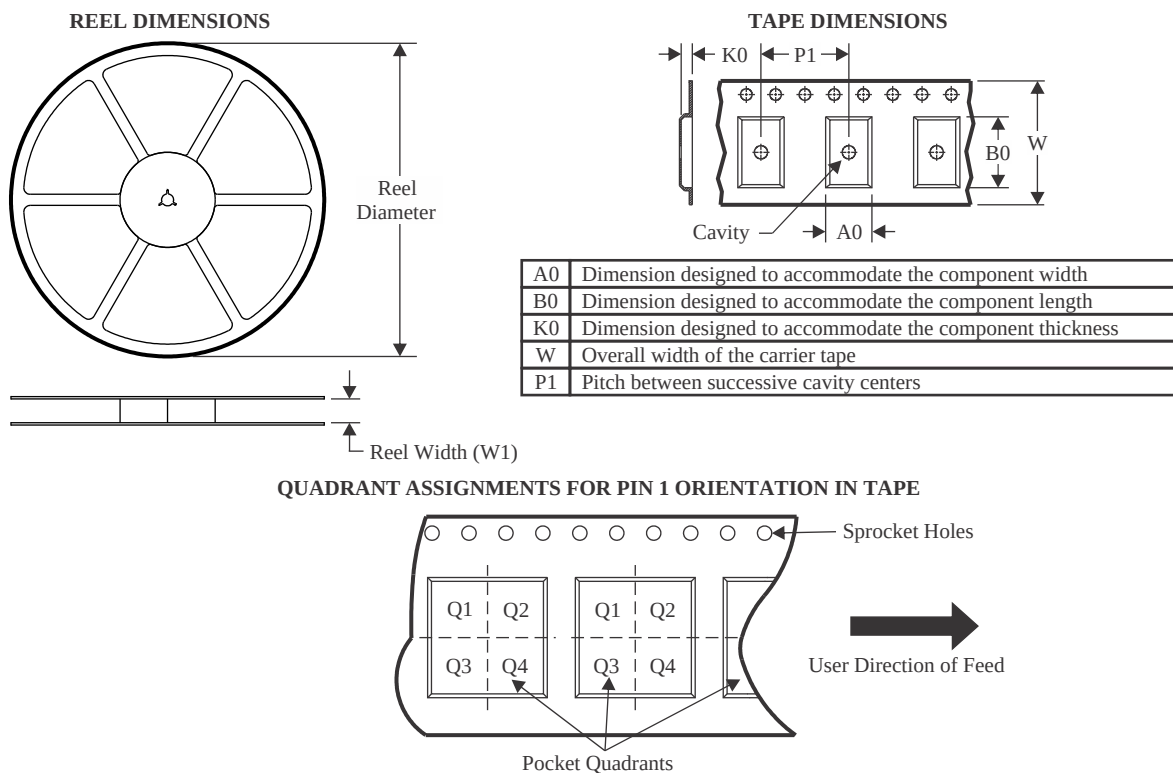
<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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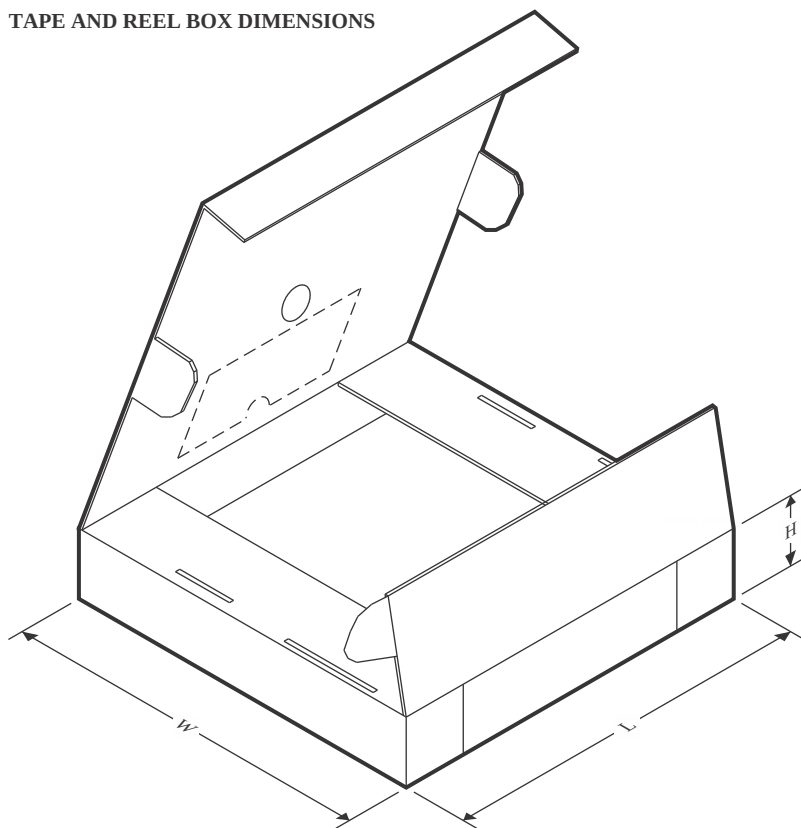
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TLC69638QDCARQ1 | HTSSOP       | DCA             | 56   | 2500 | 330.0              | 24.4               | 8.9     | 14.7    | 1.4     | 12.0    | 24.0   | Q1            |
| TLC69638QRTQRQ1 | QFN          | RTQ             | 56   | 3500 | 330.0              | 16.4               | 8.3     | 8.3     | 1.1     | 12.0    | 16.0   | Q2            |

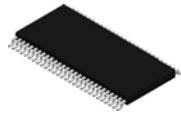
## TAPE AND REEL BOX DIMENSIONS



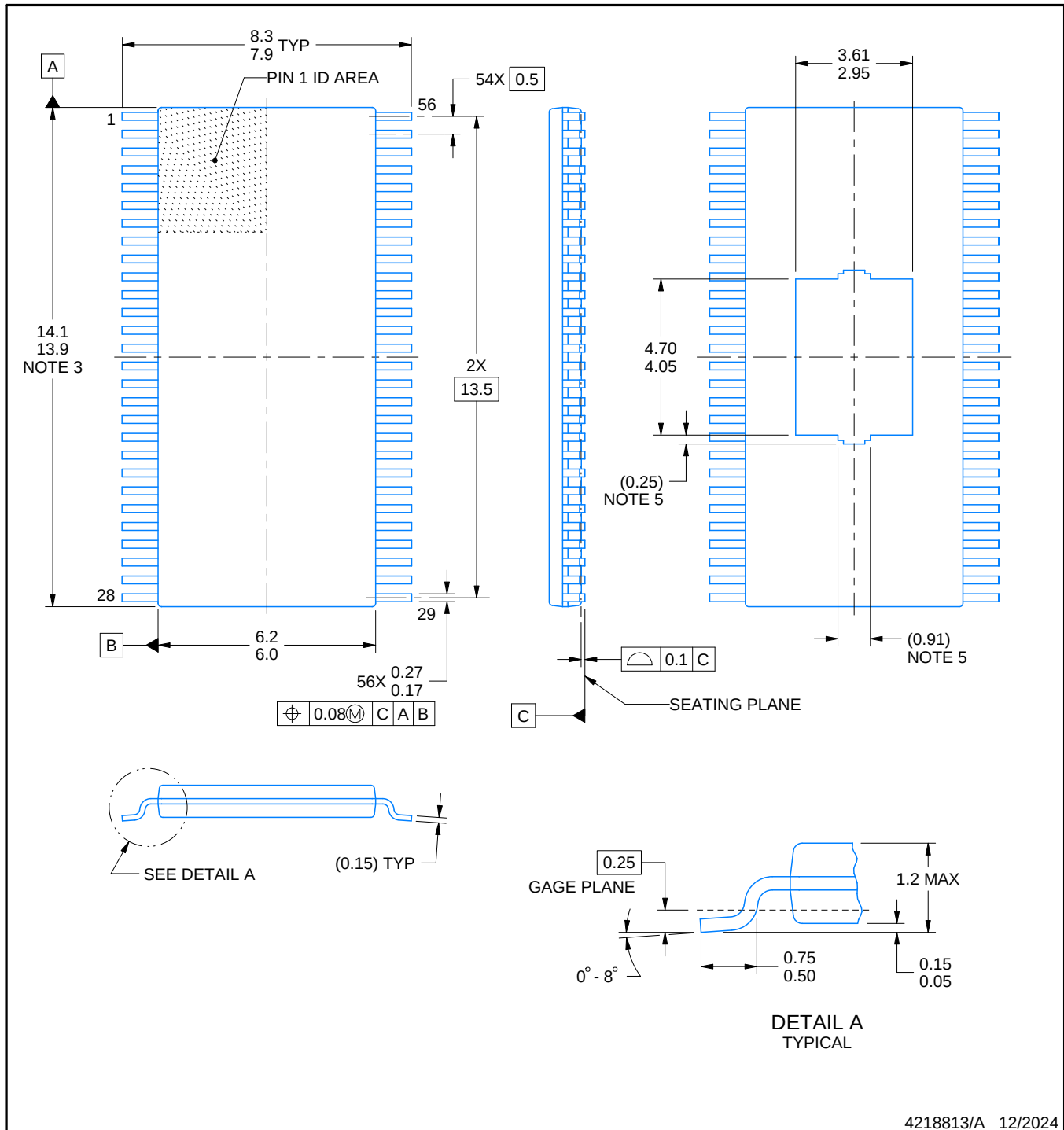
\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TLC69638QDCARQ1 | HTSSOP       | DCA             | 56   | 2500 | 356.0       | 356.0      | 45.0        |
| TLC69638QRTQRQ1 | QFN          | RTQ             | 56   | 3500 | 360.0       | 360.0      | 36.0        |



**DCA0056F****PowerPAD™ TSSOP - 1.2 mm max height****PACKAGE OUTLINE**

PLASTIC SMALL OUTLINE



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**NOTES:**

PowerPAD is a trademark of Texas Instruments.

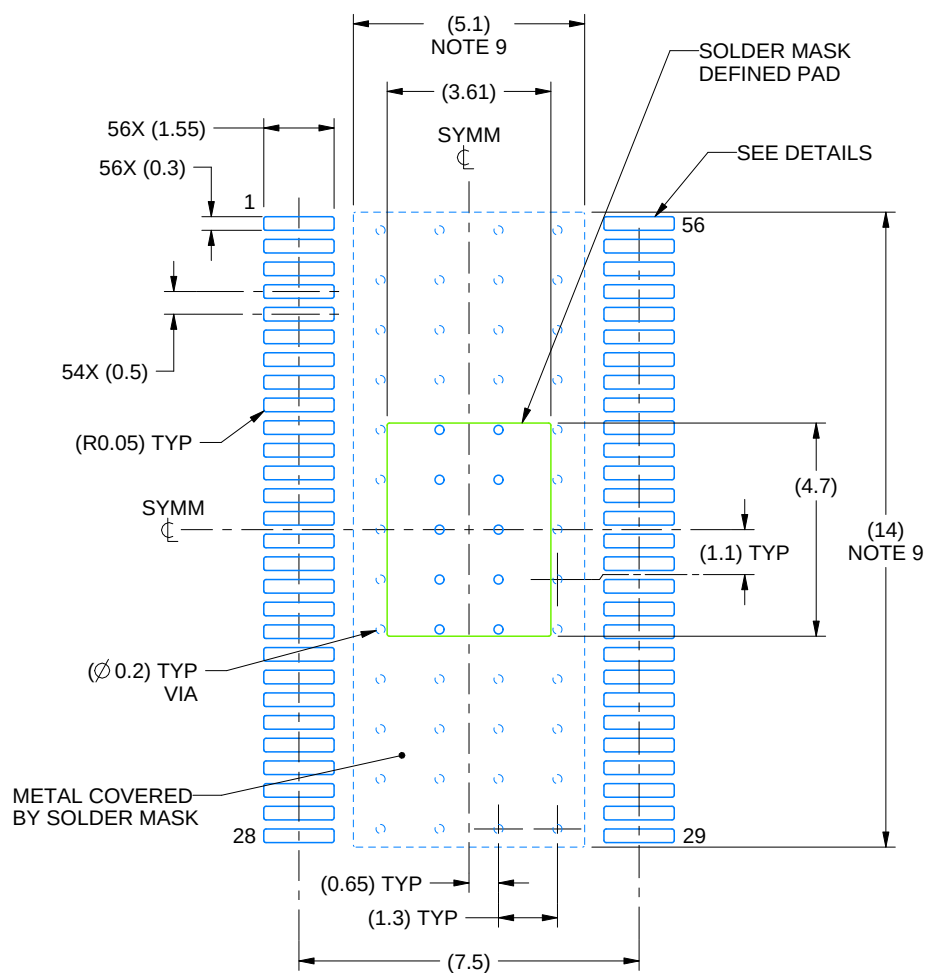
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may not present.

# EXAMPLE BOARD LAYOUT

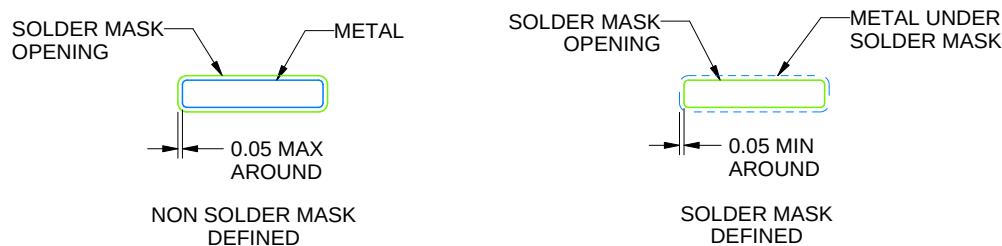
DCA0056F

PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

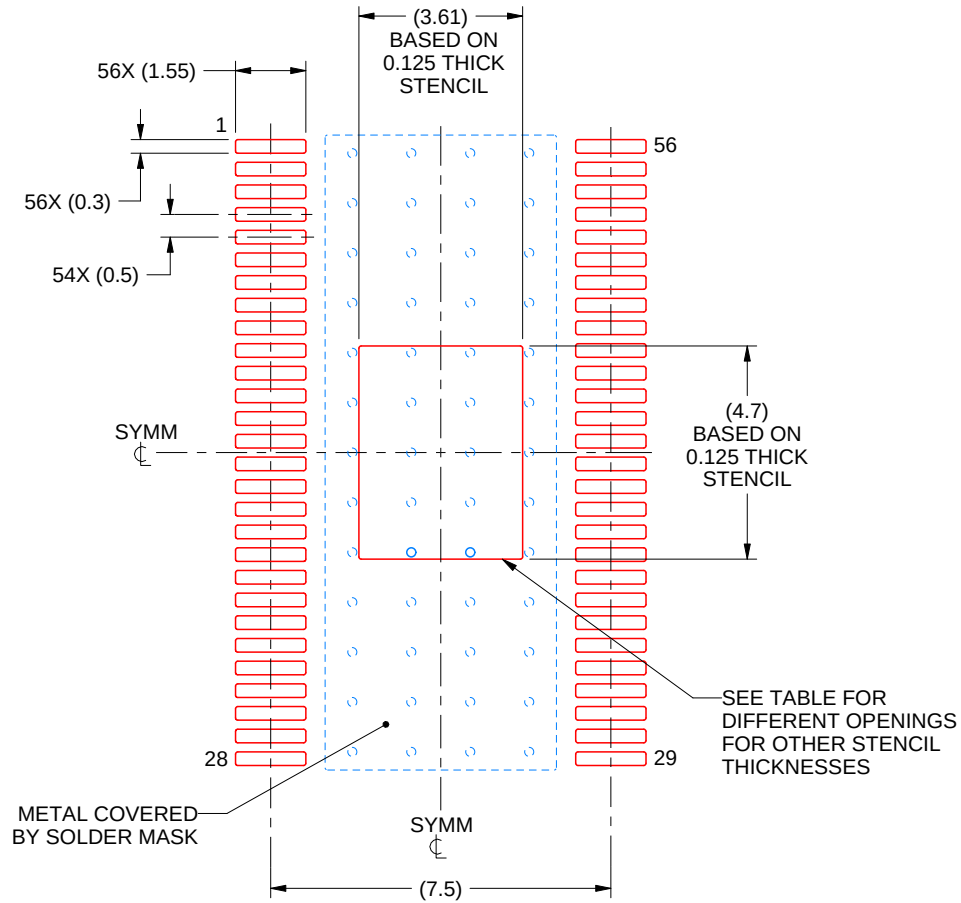
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
9. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

DCA0056F

PowerPAD™ TSSOP - 1.2 mm max height

PLASTIC SMALL OUTLINE



**SOLDER PASTE EXAMPLE**  
EXPOSED PAD  
100% PRINTED SOLDER COVERAGE BY AREA  
SCALE:6X

| STENCIL THICKNESS | SOLDER STENCIL OPENING |
|-------------------|------------------------|
| 0.1               | 4.04 X 5.25            |
| 0.125             | 3.61 X 4.70 (SHOWN)    |
| 0.15              | 3.30 X 4.29            |
| 0.175             | 3.95 X 3.97            |

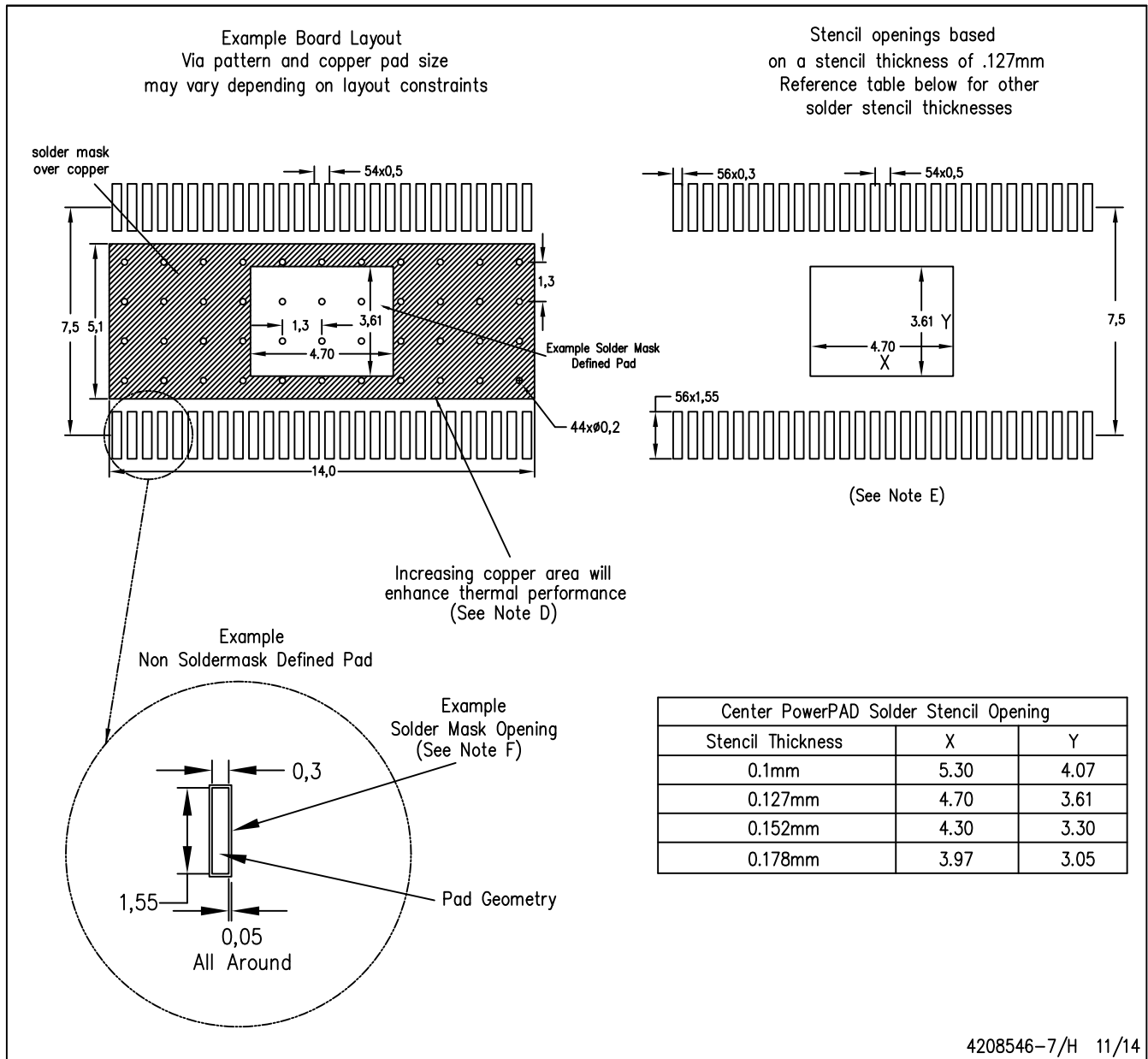
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NOTES: (continued)

10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

DCA (R-PDSO-G56)

PowerPAD™ PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

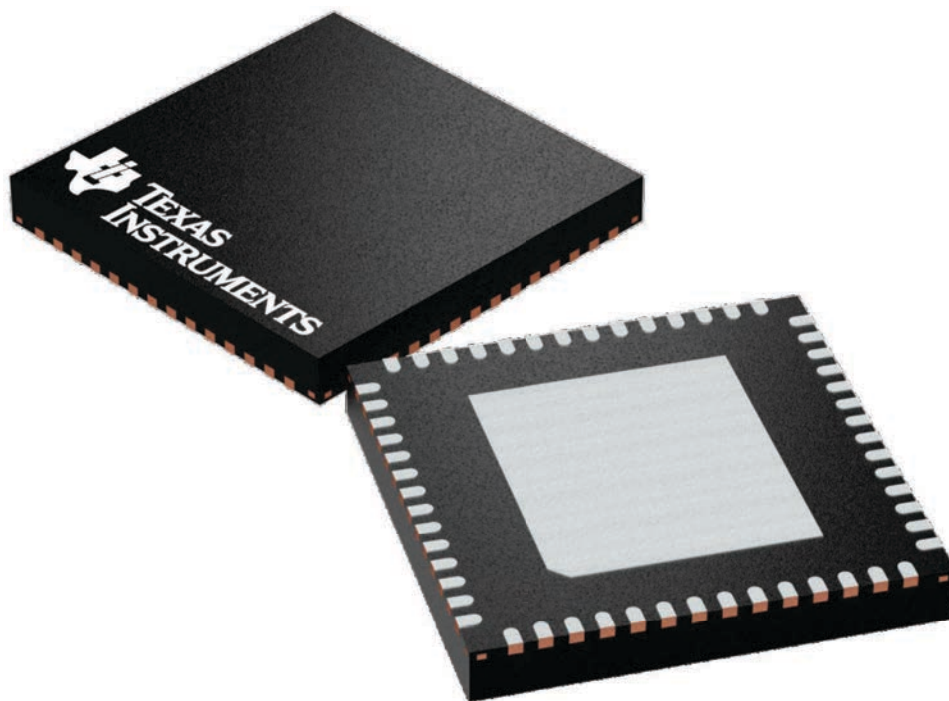
## GENERIC PACKAGE VIEW

**RTQ 56**

**VQFN - 1 mm max height**

8 x 8, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4224653/A

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.







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